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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
10/649,958	08/28/2003	Mohamad A. Shaheen	42P14710	7075	
7590 07/27/2005			EXAMINER		
Michael A. Bernadicou			WILSON, CHRISTIAN D		
BLAKELY, SO	OKOLOFF, TAYLOR &	ZAFMAN LLP			
Seventh Floor			ART UNIT	PAPER NUMBER	
12400 Wilshire Boulevard			2891		
Los Angeles, CA 90025			DATE MAIL ED 07/07/000	-	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	•	Application No.	Applicant(s)	Ap			
Office Action Summary		10/649,958	SHAHEEN ET AL.				
		Examiner	Art Unit				
		Christian Wilson	2891				
Period f	The MAILING DATE of this communication reply	n appears on the cover sheet v	vith the correspondence add	iress			
A SH THE - Exte afte - If Ni - Fail Any	HORTENED STATUTORY PERIOD FOR F MAILING DATE OF THIS COMMUNICAT ensions of time may be available under the provisions of 37 or r SIX (6) MONTHS from the mailing date of this communicati e period for reply specified above is less than thirty (30) days of period for reply is specified above, the maximum statutory ure to reply within the set or extended period for reply will, by reply received by the Office later than three months after the ned patent term adjustment. See 37 CFR 1.704(b).	ION.  FR 1.136(a). In no event, however, may a on.  , a reply within the statutory minimum of the period will apply and will expire SIX (6) MC statute, cause the application to become A	reply be timely filed irty (30) days will be considered timely. NTHS from the mailing date of this con NBANDONED (35 U.S.C. § 133).				
Status							
1)[🛛	Responsive to communication(s) filed on	13 May 2005					
· —	· · · · · · · · · · · · · · · · · · ·	This action is non-final.					
3)	,		tters, prosecution as to the	merits is			
-/-	3) Since this application is in condition for allowance except for formal matters, prosecution as to the mer closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Dienoeit	tion of Claims	,,					
·		5 47 40 51 and 52 56 inter-	anding in the confication	•			
4)[	Claim(s) <u>1,3-5,7-19,21-23,25-29,31-33,33</u> 4a) Of the above claim(s) is/are with		enumy in the application.				
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· ·	5)  Claim(s) is/are allowed. 6)  Claim(s) <u>1,3-5,7-19,21-23,25-29,31-33,35-47,49-51 and 53-56</u> is/are rejected. 7)  Claim(s) is/are objected to.						
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′=	Claim(s) are subject to restriction a	and/or election requirement.		•			
Annlicat	tion Papers		·.				
	-	minor					
·	The specification is objected to by the Exa The drawing(s) filed on <u>13 May 2005</u> is/ar		acted to by the Everniner				
Ю	Applicant may not request that any objection t						
	Replacement drawing sheet(s) including the c		• •	P 1 121/d)			
11)	The oath or declaration is objected to by the	•	· · · · ·				
		no Examinor, note the attacht		. IOE.			
Priority	under 35 U.S.C. § 119						
•	Acknowledgment is made of a claim for fo	reign priority under 35 U.S.C.	§ 119(a)-(d) or (f).				
a)	☐ All b)☐ Some * c)☐ None of:	annata kana l		•			
	1. Certified copies of the priority docu		Analinatine NI-				
	2. Certified copies of the priority docu			Stone			
	3. Copies of the certified copies of the	· ·	n received in this mational s	olage			
*	application from the International B See the attached detailed Office action for		t received				
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	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-94		Summary (PTO-413) (s)/Mail Date				
3) 🔲 Infor	mation Disclosure Statement(s) (PTO-1449 or PTO/S	-/	Informal Patent Application (PTO-	-152)			
	er No(s)/Mail Date	6) 🔲 Other:	·				

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#### **DETAILED ACTION**

## Official Notice

1. Official notice is taken of the following material properties:

Band gap energy  $(E_g)$  of silicon (Si) = 1.12 eV

Band gap energy (Eg) of silicon germanium (SiGe) < 1.00 eV

These properties were taken from Sze (*Physics of Semiconductor Devices*, pg. 850) and People (*Physics and Applications of Ge<sub>x</sub>Si<sub>1-x</sub>/Si Strained-Layer Heterostructures*, Figures 10 and 11).

## Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 3. Claims 1, 5, 7, 8, 19, 23, 25, 29, 31 33, 35, 36, 47, 49 51, and 53 56 are rejected under 35 U.S.C. 102(b) as being anticipated by Henley *et al*.

Henley et al. (US 6,290,804) discloses a method comprising impinging laser energy [column 7, line 17] on a substrate 10 and effecting laser-induced cleaving of the substrate [column 7, line 14] by stoichiometrically designing a composition of the material to substantially match a bond breaking energy involving the material to the laser energy and selecting the

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predetermined laser energy to match the bond-breaking threshold energy of the material [column 3, lines 35-55].

Regarding claim 5, Henley *et al.* further discloses the laser energy induces selective bond breaking at an interface of the host material of the substrate and the predetermined material to effect cleaving along the interface [column 4, lines 50-55].

Regarding claim 7, Henley *et al.* further discloses balancing the stoichiometric composition of the material to the laser energy to effect a cleave yield [column 3, line 50].

Regarding claim 8, Henley *et al.* further discloses bonding the substrate to a receiving substrate prior to cleaving where the cleaved layer remains bonded to the substrate [column 9, lines 25-40].

Regarding claim 19, Henley *et al.* further discloses impinging the laser energy on the side edge of the substrate [Figure 7].

Regarding claim 23, Henley *et al.* further discloses the laser energy induces selective bond breaking at an interface of the host material of the substrate and the predetermined material to effect cleaving along the interface [column 4, lines 50-55].

Regarding claim 25, Henley *et al.* further discloses balancing the stoichiometric composition of the material to the laser energy to effect a cleave yield [column 3, line 50].

Regarding claim 28, Henley *et al.* further discloses bonding the substrate to a receiving substrate prior to cleaving where the cleaved layer remains bonded to the substrate [column 9, lines 25-40].

Regarding claims 29, 31 - 33, 35, 36, 47, 49 - 51, and 53 - 56, Henley *et al.* discloses a silicon-on-insulator device in an electronic package [column 1, lines 15-25]. It is noted that product-by-process claims are not limited to the manipulations of the recited steps, only the structure implied by the steps. "[E]ven though product-by-process claims are limited by and

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defined by the process, determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." In re Thorpe, 777 F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985)

Since the recited structures are the same as the product as disclosed by Henley *et al.*, the claims is unpatentable over Henley *et al.* 

## Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 3, 4, 21, and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Henley *et al.* in view of Roche.

Henley *et al.* further teaches a silicon substrate [column 3, line 61] and a predetermined material which is hydrogen [column 4, line 35], but does not discuss a predetermined material which is germanium or a laser with an energy greater than the band gap of SiGe or smaller than Si or is infrared. Roche (US 2003/0162367) teaches a Nd:YAG laser which is an infrared laser with an energy of 1.06 eV and a Ge material [0065, 0026]. It would have been obvious to one of ordinary skill in the art to use the laser and material of Roche since Roche teaches that the laser and material provides short pulses which are absorbed in the weakened zone of the material.

6. Claims 9 - 12, 15 - 18, 37 - 40, and 43 - 45 are rejected under 35 U.S.C. 103(a) as being unpatentable over Henley *et al.* in view of Kelly *et al.* 

Regarding claims 9 - 11, Henley *et al.* teaches laser-induced cleaving but does not discuss plural interfering laser beams with specifically tuned energies that forms a interference profile. Kelly *et al.* (US 6,740,604) teaches a multiple laser cleaving method with simultaneous laser irradiation with plural interfering laser beams [column 3, lines 55-60]. It would have been obvious to one of ordinary skill in the art to use the laser method of Kelly *et al.* in the method of Henley *et al.* since the interfering beams produces an increase in the local radiation.

Regarding claim 15, Henley *et al.* further teaches the laser energy induces selective bond breaking at an interface of the host material of the substrate and the predetermined material to effect cleaving along the interface [column 4, lines 50-55].

Regarding claim 16, Henley *et al.* further teaches stoichiometrically designing a composition of the material to substantially match a bond breaking energy involving the material to the laser energy and selecting the predetermined laser energy to match the bond-breaking threshold energy of the material [column 3, lines 35-55].

Regarding claim 17, Henley *et al.* further teaches balancing the stoichiometric composition of the material to the laser energy to effect a cleave yield [column 3, line 50].

Regarding claim 18, Henley *et al.* further teaches bonding the substrate to a receiving substrate prior to cleaving where the cleaved layer remains bonded to the substrate [column 9, lines 25-40].

Regarding claims 37 - 40 and 43 - 45, Henley *et al.* teachess a silicon-on-insulator device in an electronic package [column 1, lines 15-25]. It is noted that product-by-process claims are not limited to the manipulations of the recited steps, only the structure implied by the steps. "[E]ven though product-by-process claims are limited by and defined by the process,

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determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." In re Thorpe, 777 F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985)

Since the recited structures are the same as the product as disclosed by Henley *et al.*, the claims is unpatentable over Henley *et al.* 

7. Claims 13, 14, 41, and 42 are rejected under 35 U.S.C. 103(a) as being unpatentable over Henley et al. and Kelly et al. as applied to claim 12 above, and further in view of Roche.

Henley *et al.* further teaches a silicon substrate [column 3, line 61] and a predetermined material which is hydrogen [column 4, line 35], but does not discuss a predetermined material which is germanium or a laser with an energy greater than the band gap of SiGe or smaller than Si or is infrared. Roche (US 2003/0162367) teaches a Nd YAG laser which is an infrared laser with an energy of 1.06 eV and a Ge material [0065, 0026]. It would have been obvious to one of ordinary skill in the art to use the laser and material of Roche since Roche teaches that the laser and material provides short pulses which are absorbed in the weakened zone of the material.

Regarding claims 41 and 42, Henley *et al.* teachess a silicon-on-insulator device in an electronic package [column 1, lines 15-25]. It is noted that product-by-process claims are not limited to the manipulations of the recited steps, only the structure implied by the steps. "[E]ven though product-by-process claims are limited by and defined by the process, determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." In re Thorpe, 777 F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985)

Since the recited structures are the same as the product as disclosed by Henley *et al.*, the claims is unpatentable over Henley *et al.* 

8. Claims 26 and 27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Henley et al. in view of Nakano et al.

Henley *et al.* teaches an ion implantation method with hydrogen which forms microdefects at the cleave plane [column 4, lines 60-65], but does not discuss forming micro-voids. Nakano *et al.* (US 2003/0153162) teaches an implantation method which forms micro-voids [0024]. It would have been obvious to one of ordinary skill in the art that the method of Henley *et al.* would produce the micro-voids of Nakano *et al.* at the cleave plane since Nakano *et al.* teaches that ion implantation causes micro-voids by channeling of ions in the material layer [0047].

#### Response to Arguments

9. Applicant's arguments filed May 13, 2005 have been fully considered but they are not persuasive.

Regarding claim 1, applicant argues that Henley teaches selecting the energy level of the laser to match the bond breaking strength of the cleaved material. Applicant argues that selecting the energy level of the laser is not the same as selecting the laser wavelength. It is well known in physics (as described by Planck's formula) that the energy of any electromagnetic radiation is described by the formula:

$$E = hc / \lambda$$

where h is Planck's constant, c is the speed of light, and  $\lambda$  is the wavelength of the light. Therefore, selecting the energy of the laser light is equivalent to selecting the wavelength of the light. Further, applicant argues that does not select the laser wavelength of the light based on the

stoichiometry of the cleaved material. Webster's defines stoichiometry as "the quantitative relationship between constituents in a chemical substance". In Henley *et al.*, the bond breaking energy of the laser light is directly related to the quantitative relationship of the constituents of the cleaved substance [column 3, lines 50-60]. Therefore, the laser light wavelength is matched to the stoichiometrically designed cleave layer [column 4, lines 50-65] in order to more effectively cleave the substrate material.

The arguments regarding claims 9 - 18 are most in light of the new grounds of rejection.

#### Conclusion

10. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Christian Wilson whose telephone number is (571) 272-1886. The examiner can normally be reached on weekdays, 7:30 AM to 4 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571) 272-1722. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Christian Wilson, Ph.D. Primary Examiner

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